TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

## TD62101P,TD62101F,TD62103P,TD62103F TD62104P,TD62104F,TD62105P,TD62105F

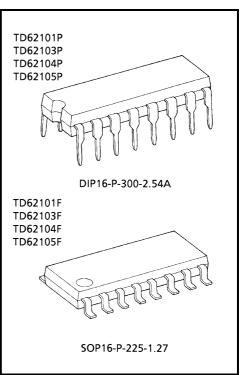
## 7CH DARLINGTON SINK DRIVER

The TD62101P / F series are high-voltage, high-current darlington drivers comprised of seven NPN darlington pairs.

## FEATURES

- Output current (single output) : 500 mA (max)
- High sustaining voltage output: 25 V (min)
- Inputs compatible with various types of logic.
- Package type-P : DIP-16 pin.
- Package type-F : SOP-16 pin.

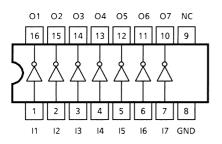
TYPE	INPUT BASE RESISTOR	DESIGNATION
TD62101P / F	External	General Purpose
TD62103P / F	2.7kΩ	TTL, 5 V CMOS
TD62104P / F	10.5kΩ	6~15 V CMOS, PMOS
TD62105P / F	20kΩ	12~25 V CMOS, PMOS



Weight

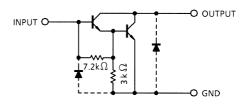
DIP16-P-300-2.54A : 1.11 g (typ.) SOP16-P-225-1.27 : 0.16 g (typ.)

#### **PIN CONNECTION (TOP VIEW)**



#### SCHEMATICS (EACH DRIVER)

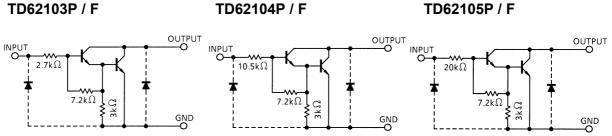
#### TD62101P / F



Note: The input and output parasitic diodes cannot be used as clamp diodes.

#### SCHEMATICS (EACH DRIVER)

TD62103P / F



Note: The input and output parasitic diodes cannot be used as clamp diodes.

## MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTICS	SYMBOL	RATING	UNIT		
Output Sustaining Voltage		V <sub>CE (SUS)</sub>	-0.5~25	V	
Output Current		I <sub>OUT</sub>	500	mA / ch	
Input Voltage	V <sub>IN</sub> (Note 1)	-0.5~30	V		
Input Current	I <sub>IN</sub> (Note 2)	25	mA		
Power Dissipation	Р	<b>D</b> -	1.0	w	
	F	PD	0.625 (Note 3)	vv	
Operating Temperature	Р	т	-30~75	°C	
Operating Temperature	F	T <sub>opr</sub>	-40~85		
Storage Temperature	T <sub>stg</sub>	-55~150	°C		

Note 1: Except TD62101P / F

Note 2: Only TD62101P / F

Note 3: On Glass Epoxy PCB (30 × 30 × 1.6 mm Cu 50%)

#### **RECOMMENDED OPERATING CONDITIONS** $(Ta = -40 \sim 85^{\circ}C \text{ and } Ta = -30 \sim 75^{\circ}C \text{ for only Type-P})$

CHARACTERISTIC		SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT		
Output Sustaining Voltage		V <sub>CE (SUS)</sub>		0	_	25	V		
				DC 1 Circuit	0	_	350	mA /	
Output Current		lout	T <sub>pw</sub> = 25 ms, Duty = 10% 7 Circuits, Ta = 85°C, T <sub>j</sub> = 120°C	0	_	300	ch		
Input Voltage Except TD62101P / F		V <sub>IN</sub>		0	_	20	V		
Input Current Only TD62101P / F		I <sub>IN</sub>			_	10	mA		
Power Dissipation		Р	D-			_	0.44	w	
		F	P <sub>D</sub>	(Note)		_	0.325	vv	

Note: On Glass Epoxy PCB (30 × 30 × 1.6 mm Cu 50%)

## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC			SYMBOL	TEST CIR-	TEST CONDITION		MIN	TYP.	MAX	UNIT
		OTHEOL	CUIT	1201 00	TEOR CONDITION			IVI/-VX	ONT	
Output Leakage P		I <sub>CEX</sub>	1	V <sub>CE</sub> = 25 V I <sub>IN</sub> = 0	Ta = 75°C	—	—	100	μA	
Current F					Ta = 85°C	—	—	100		
				2	I <sub>OUT</sub> = 350 mA, I <sub>IN</sub> = 600 μA		_	1.3	2.2	V
Collector-	-Emitter Satu	ration Voltage	V <sub>CE (sat)</sub>		$I_{OUT}$ = 200 mA, $I_{IN}$ = 400 $\mu$ A		—	1.1	2.0	
					I <sub>OUT</sub> = 100 mA, I <sub>IN</sub> = 200 μA		—	1.0	1.8	
DC Curre	nt Transfer R	atio	h <sub>FE</sub>	2	V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 350 mA		1000	—		
		TD62101P / F			V <sub>IN</sub> = 1.5 V, I <sub>OUT</sub> = 350 mA		—	0.25	-	mA
		10021011 /1			V <sub>IN</sub> = 1.75 V, I <sub>OUT</sub> = 350 mA		—	1.00		
	Output On	TD62103P / F	I <sub>IN (ON)</sub>	3	V <sub>IN</sub> = 2.4 V, I <sub>OUT</sub> = 350 mA		—	0.4	0.7	
Input Current		TD62104P / F			V <sub>IN</sub> = 13.5 V, I <sub>OUT</sub> = 350 mA		—	1.2	1.7	
		TD62105P / F			V <sub>IN</sub> = 20.0 V, I <sub>OUT</sub> = 350 mA		_	1.0	1.5	
	Output Off	Р		4	I <sub>OUT</sub> =	Ta = 75°C	50	65	-	
		F	IN (OFF)	4	500 µA	Ta = 85°C	50	65	_	μA
	TD62103P / F					_	_	2.1		
		TD62104P / F				I <sub>OUT</sub> = 125 mA	_	_	4	
		TD62105P / F TD62103P / F				_	_	6.4	1	
					V <sub>CE</sub> = 2 V	l <sub>OUT</sub> = 250 mA	_	_	2.7	V
Input Voltage	Output On	TD62104P / F	62104P / F V <sub>IN (ON)</sub>	5			_	—	7	
Unage		TD62105P / F					_	—	12	
		TD62103P / F				I <sub>OUT</sub> = 350 mA	_	_	3.3	
		TD62104P / F					_	_	8.8	
		TD62105P / F					_	_	15	
Input Capacitance		C <sub>IN</sub>	6	V <sub>IN</sub> = 0, f = 1 MHz		_	15	_	pF	
Turn-On Delay		t <sub>ON</sub>	_	$V_{OUT}$ = 25 V, R <sub>L</sub> = 70 Ω C <sub>L</sub> = 15 pF		_	0.1	_	μs	
Turn-Off	Turn-Off Delay					- 7	_	0.2		_

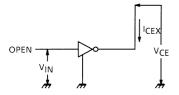
## **TEST CIRCUIT**

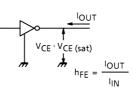
1. I<sub>CEX</sub>

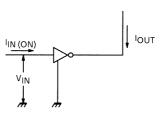
2. h<sub>FE</sub>, V<sub>CE (sat)</sub>

IN.

3. I<sub>IN (ON)</sub>

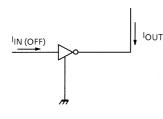


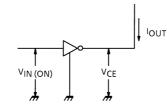




## **TEST CIRCUIT**

#### 4. IIN (OFF)

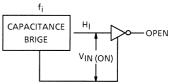




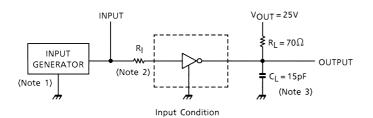
5. VIN (ON)

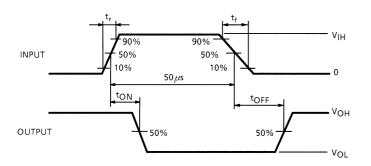


6. C<sub>IN</sub>



## 7. t<sub>ON</sub>, t<sub>OFF</sub>





- Note 1: Pulse Width 50  $\mu s,$  Duty Cycle 10% Output Impedance 50  $\Omega,$   $t_{f}$   $\leq$  5 ns,  $t_{f}$   $\leq$  10 ns
- Note 2: See right.
- Note 3:  $\,C_L$  includes probe and jig capacitance.

### INPUT CONDITION

TYPE NUMBER	RI	V <sub>IH</sub>		
TD62101P / F	2.7 kΩ	3 V		
TD62103P / F	0 Ω	3 V		
TD62104P / F	0 Ω	8 V		
TD62105P / F	0 Ω	15 V		

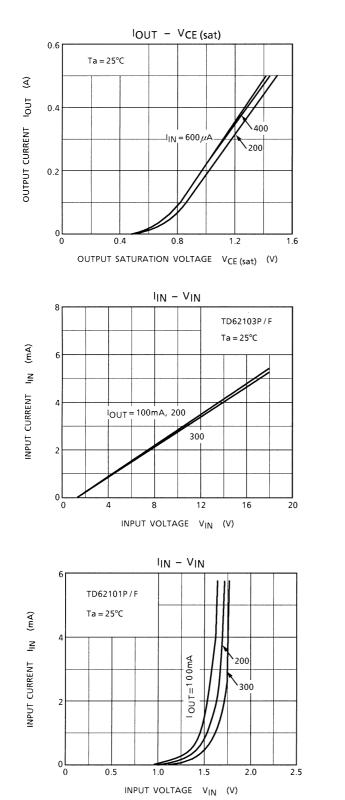
#### **PRECAUTIONS for USING**

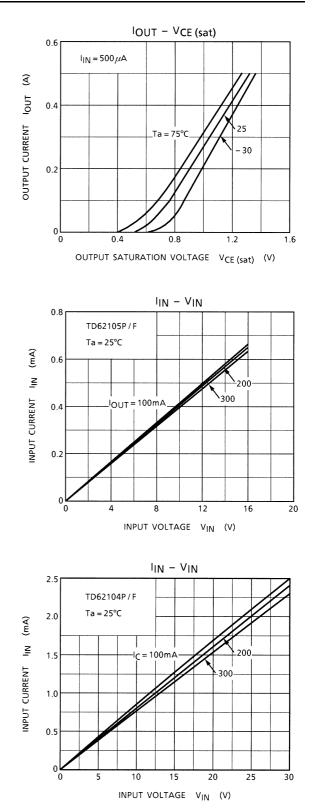
This IC does not include built-in protection circuits for excess current or overvoltage.

If this IC is subjected to excess current or overvoltage, it may be destroyed.

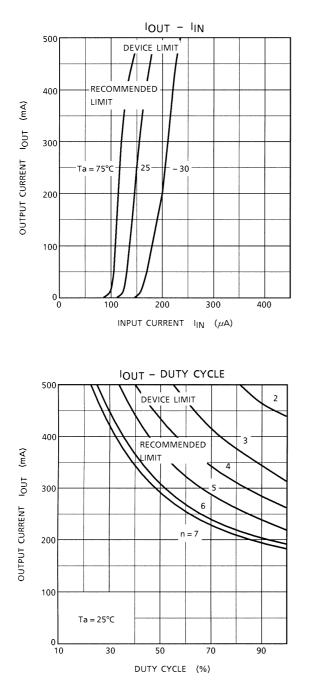
Hence, the utmost care must be taken when systems which incorporate this IC are designed.

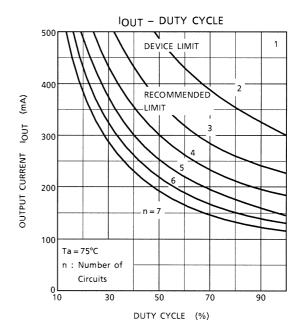
Utmost care is necessary in the design of the output line, GND line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

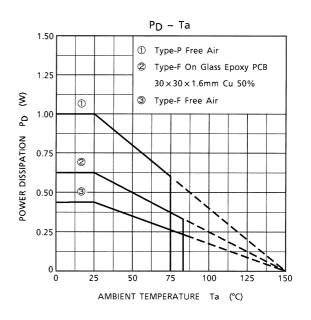




# <u>TOSHIBA</u>



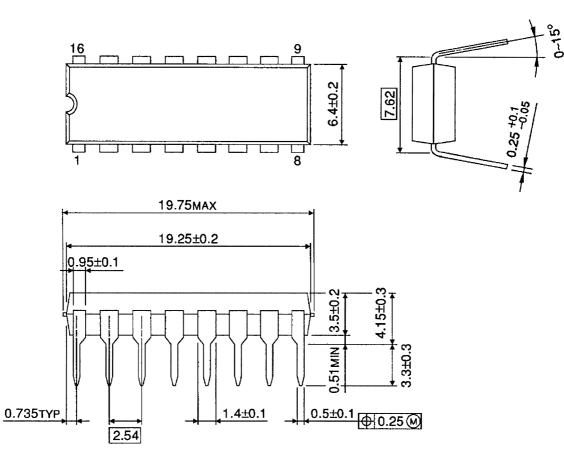




## PACKAGE DIMENSIONS

DIP16-P-300-2.54A

Unit: mm

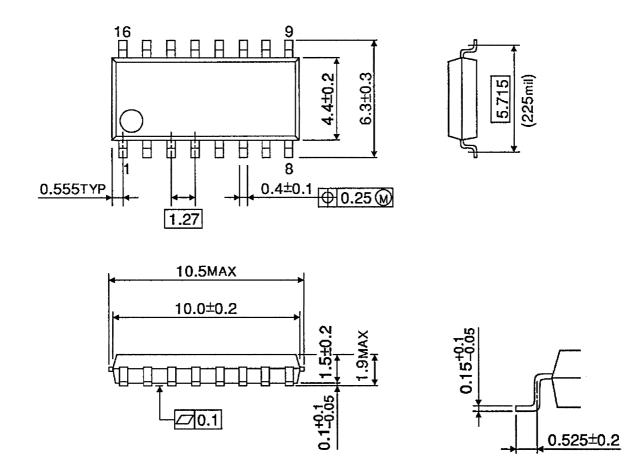


Weight: 1.11 g (typ.)

#### PACKAGE DIMENSIONS

SOP16-P-225-1.27

Unit: mm



Weight: 0.16 g (typ.)

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